10817659 - GAU: 1795

Doc description: Information Disclosure Statement (IDS) Filed

Approved for use through 04/30/2008. OMB 0651-0031 U.S. Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

| INFORMATION DISCLOSUR | E |
|--|----|
| STATEMENT BY APPLICAN | T |
| (Not for submission under 37 CFR 1.99 | 9) |

| Application Number | | 10817659 | | | | | |
|----------------------|-------------------|-----------------|--|--|--|--|--|
| Filing Date | | 2004-04-02 | | | | | |
| First Named Inventor | Gregory J. Wilson | | | | | | |
| Art Unit | | 1795 | | | | | |
| Examiner Name | Nicholas A. Smith | | | | | | |
| Attorney Docket Numb | er | 63857.8157.US04 | | | | | |

| U.S.PATENTS | | | | | | | | | Remove | | | |
|--|------------|---|-------------------------------------|-------------------|---------------|-------------------------------|--|---------|---|----|--|--|
| Examiner Initial* | Cite No | Patent Number | Kind Code ¹ | Issue D | Date | Name of Pate of cited Docu | entee or Applicant Iment | Relev | s,Columns,Lines where ant Passages or Releves Appear | | | |
| | 1 | | | | | | | | | | | |
| If you wis | h to a | dd additional U.S. Pater | nt citatio | n in f orm | ation pl | ease click the | Add button. | | Add | | | |
| U.S.PATENT APPLICATION PUBLICATIONS Remove | | | | | | | | | | | | |
| | | | Kind Code ¹ | Publica Date | ation | of cited Document | | | Pages,Columns,Lines where Relevant Passages or Relevan Figures Appear | | | |
| | 1 | | | | | | | | | | | |
| If you wis | h to a | dd additional U.S. Publi | | | | | | d butto | Remove | | | |
| Examiner Initial* | Cite No | Foreign Document Number ³ | Country Code ² i JP JP | | Kind Code4 | Publication Date | Name of Patente Applicant of cited Document | e or | Pages,Columns,Lines where Relevant Passages or Relevant Figures Appear | T5 | | |
| | 1 | 2200800 | | | | 1990-08-09 | Nippon Electric Co. Electroplating Engineers of Japan Limited | | | × | | |
| | 2 | 2001-64795 | | | | 2001-03-13 | | | | | | |
| | 3 | 11-350185 | | | | 1999-12-21 | Electroplating Engl Japan Co. | of | | | | |

| INFORMATION DISCLOSURE | | | | Filing | Date | | | 2004-04-02 | | | | |
|---|--|---|--------------------|---------------------------|---------|----------|--------------|-----------------|-------------------------|----------|----|---|
| | | | | First Named Inventor Greg | | | | gory J. Wilson | | | | |
| STATEMENT BY APPLICANT | | | Art Unit | | | | 1795 | | | | | |
| (Not for submission under 37 CFR 1.99) | | | | Examiner Name Nich | | | | cholas A. Smith | | | | |
| | | | | | | ey Doc | ket Numb | er | 63857.8157.US04 | | | |
| | | | | | | | | | | | | |
| | | | | | | | | _ | | 1 | | _ |
| | 4 | 2000- | 256896 | JP | JP | | 2000-09-1 | 9 E | Ebara Corp. | | | |
| | 5 | 2000- | 087299 | JP | | | | | Ebara Corp. | | × | |
| | 6 | 71972 | 299 | JP | | | | | Casio Computer Co. Ltd. | | | |
| | 7 | 2004- | 097856 | JP | | | 2004-04-0 | 2 | Masuda Shokai:KK | | | × |
| If you wis | h to ac | ld add | litional Foreign P | atent Doc | ument | citation | informatio | n plea | ase click the Add butto | n Add | | |
| | | | | NON- | PATEN | NT LITE | RATURE | DOC | UMENTS | Remove | | |
| Examiner Initials* | Cite No | Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc), date, pages(s), volume-issue number(s), publisher, city and/or country where published. | | | | | | | | T5 | | |
| | 1 | Office Action issued by the Japanese Patent Office on May 26, 2008 in Japanese Patent Application No. 2003-500322. | | | | | | | | | × | |
| If you wis | h to ac | ld add | litional non-pater | t literatur | e docur | ment cit | tation infor | matio | n please click the Add | button A | id | |
| | | | | | EX | AMINE | R SIGNAT | URE | | | | |
| Examiner | Examiner Signature /Nicholas Smith/ Date Considered 12/04/2008 | | | | | | | | | | | |

Application Number

10817659

10817659 - GAU: 1795

1 See Kind Codes of USPTO Patent Documents at www.USPTO.GOV or MPEP 901.04, 2 Enter office that issued the document, by the two-letter code (WIPO Standard ST.3). 3 For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. 4 Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST.16 if possible. 5 Applicant is to place a check mark here if

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through a citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

English language translation is attached.

Receipt date: 08/07/2008